

a light emitting diode (LED) chip mounted on said first electrode pattern;
a metal wire connected to said LED chip and said second electrode pattern by wire bonding; and
a translucent resin mold which seals said LED chip and said metal wire;
wherein one notch is formed at one end of said board at said first electrode pattern side and two notches are formed at both sides of the other end of said board at said second electrode pattern side, and the positions at both ends of said translucent resin mold are arranged to the positions at both ends in a longitudinal direction of said board.

4. (Once Amended) The chip type light emitting device of claim 1, wherein said metal wire is connected to said LED chip and the surface of said second electrode pattern, which is located on a portion of said board between said two notches formed at both sides of the other end of said board at said second electrode pattern side, by wire bonding.

A copy of the marked up amended claims is attached to this response showing the changes as set forth in amended 37 C.F.R. § 1.121.

REMARKS

Claims 1-5 are pending in this application. By this Amendment, claims 1 and 4 are amended. Support for the amendments is found in the specification. No new matter is added. The above amendments and the following remarks are submitted as a full and complete response to the outstanding Office Action.

CLAIMS 1-5 CONTAIN PATENTABLE SUBJECT MATTER

The Office Action rejects claims 1, 2, 4 and 5 under 35 U.S.C. § 102(b) over JP 58-